

## ABSTRACT OF THE DISCLOSURE

In the production of a thermally conductive substrate, a thermally conductive resin sheet member attaching lead frame is provided for the purpose of suppressing the formation of resin burrs and surface stains on surfaces of the lead frame and also "Takt" for the production of the thermally conductive substrate is shortened.

There is provided a thermally conductive resin sheet member attaching lead frame wherein a lead frame comprises a thermally conductive resin sheet member and it is integrated with the thermally conductive resin sheet member on the lead frame, the thermally conductive resin sheet member being formed from a thermosetting resin mixture which comprises 70 to 90 parts by weight of an inorganic filler and 5 to 30 parts by weight of a thermosetting resin composition comprising a thermosetting resin, and the thermosetting resin is in a semi-cured state.